



## QUAD/DUAL SUPERCAPACITOR AUTO BALANCING (SAB™) MOSFET ARRAY

### GENERAL DESCRIPTION

The ALD810030/ALD910030 are additional members of the ALD8100xx (quad) and ALD9100xx (dual) family of Supercapacitor Auto Balancing MOSFETs, or SAB™ MOSFETs. SAB MOSFETs are built with production proven EPAD® technology and are designed to address voltage and leakage-current balancing of supercapacitors connected in series. Supercapacitors, also known as ultracapacitors or supercaps, connected in series can be leakage-current balanced by using a combination of one or more devices connected across each supercapacitor stack to prevent overvoltages.

The ALD810030 offers a set of unique, precise operating voltage and current characteristics for each of four SAB MOSFET devices, as shown in its Operating Electrical Characteristics table. It can be used to balance up to four supercapacitors connected in series. The ALD910030 has its own set of unique precision Operating Electrical Characteristics for each of its two SAB MOSFET devices, suitable for up to two series-connected supercapacitors.

Each SAB MOSFET features a precision gate threshold voltage in the Vt mode, which is 3.00V when the gate-drain source terminals (VGS = VDS) are connected together at a drain-source current of  $I_{DS(ON)} = 1 \mu A$ . In this mode, input voltage  $V_{IN} = V_{GS} = V_{DS}$ . Different VIN produces an Output Current IOUT = IDS(ON) characteristic and results in an effective variable resistor that varies in value exponentially with VIN. This VIN, when connected across each supercapacitor in a series, balances each supercapacitor to within its voltage and current limits.

When  $V_{IN}$  = 3.00V is applied to an ALD810030/ALD910030, its  $I_{OUT}$  is  $1\mu A.$  For a 100mV increase in  $V_{IN}$ , to 3.10V,  $I_{OUT}$  increases by about tenfold. For an additional increase in VIN to 3.22V for the ALD910030 (3.24V for the ALD810030), I<sub>OUT</sub> increases one hundredfold, to  $100\mu A.$  Conversely, for a 100mV decrease in  $V_{IN}$  to 2.90V, IOUT decreases to one tenth of its previous value, to 0.1µA. Another 100mV decrease in input voltage would reduce IOUT to 0.01µA. Hence, when an ALD810030/ALD910030 SAB MOSFET is connected across a supercapacitor that charges to less than 2.80V, it would dissipate essentially no power.

(Continued on next page)

### **PRODUCT FAMILY SPECIFICATIONS**

For more information on supercapacitor balancing, how SAB MOSFETs achieve automatic supercapacitor balancing, the device characteristics of the SAB MOSFET family, product family product selection guide, applications, configurations, and package information, please download from www.aldinc.com the document:

"ALD8100xx/ALD9100xx Family of Supercapacitor Auto Balancing (SAB™) MOSFET ARRAYs

#### **ORDERING INFORMATION** ("L" suffix denotes lead-free (RoHS))

	Operating Temperature Range			
Package	0°C to +70°C	-40°C to +85°C		
	(Commercial)	(Industrial)		
16-Pin SOIC	N/A	ALD810030SCLI		
8-Pin SOIC	N/A	ALD910030SALI		

### **FEATURES & BENEFITS**

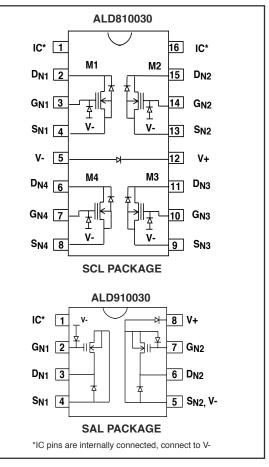
- · Simple and economical to use
- Precision factory trimmed
- Automatically regulates and balances leakage currents
- Effective for supercapacitor charge-balancing
- Balances up to 4 supercaps with a single IC package
- Balances 2-cell, 3-cell, 4-cell series-connected supercaps
- Scalable to larger supercap stacks and arrays Near zero additional leakage currents Zero leakage at 0.3V below rated voltages

- Balances series and/or parallel-connected supercaps
- Leakage currents are exponential function of cell voltages
- Active current ranges from <0.3nA to >1000μA
- · Always active, always fast response time
- · Minimizes leakage currents and power dissipation

### **APPLICATIONS**

- · Series-connected supercapacitor cell leakage balancing
- Energy harvesting
- Long term backup battery with supercapacitor outputs
- Zero-power voltage divider at selected voltages
- Matched current mirrors and current sources
- Zero-power mode maximum voltage limiter
- · Scaled supercapacitor stacks and arrays

### **PIN CONFIGURATIONS**



### **GENERAL DESCRIPTION (CONT.)**

The voltage dependent characteristic of the ALD810030/ ALD910030 on-resistance is effective in controlling excessive voltage rise across a supercapacitor when connected across it. In series-connected supercapacitor stacks, when one supercapacitor voltage rises, the voltage of the other supercapacitors drops, with the ones that have the highest leakage currents having the lowest supercapacitor voltages. The SAB MOSFETs connected across these supercapacitors would exhibit complementary opposing current levels, resulting in little additional leakage currents other than those caused by the supercapacitors themselves.

For technical assistance, please contact ALD technical support at techsupport@aldinc.com.

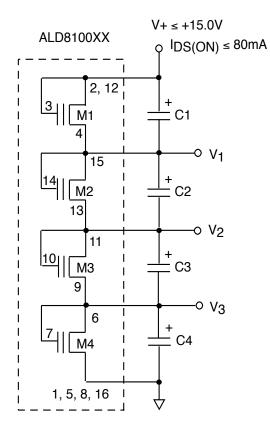
#### APPLYING THE ALD810030/ALD910030:

1) Select a maximum supercapacitor leakage current limit for any supercapacitor used in the stack. This is the same as output current,  $I_{OUT} = I_{DS(ON)}$ , of the ALD810030/ALD910030. Test that each supercapacitor leakage current meets this maximum current limit before use in the stack.

2) Determine whether the input voltage V<sub>IN</sub> (V<sub>GS</sub> = V<sub>DS</sub>) at that I<sub>OUT</sub> is acceptable for the intended application. This voltage is the same voltage as the maximum desired operating voltage of the supercapacitor. For example, with the ALD810030, I<sub>OUT</sub> =  $1.0\mu$ A corresponds to V<sub>IN</sub> = 3.00V.

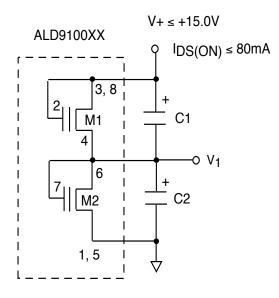
3) Determine that the operating voltage margin, due to various tolerances and/or temperature effects, is adequate for the intended operating environment of the supercapacitor.

# SCHEMATIC DIAGRAM OF A TYPICAL CONNECTION FOR A FOUR-SUPERCAP STACK



1-16 DENOTES PACKAGE PIN NUMBERS C1-C4 DENOTES SUPERCAPACITORS

# SCHEMATIC DIAGRAM OF A TYPICAL CONNECTION FOR A TWO-SUPERCAP STACK



## 1-8 DENOTES PACKAGE PIN NUMBERS C1-C2 DENOTES SUPERCAPACITORS

## ABSOLUTE MAXIMUM RATINGS

V+ to V- voltage	15.0V
Drain-Source voltage, V <sub>DS</sub>	10.6V
Gate-Source voltage, V <sub>GS</sub>	10.6V
Operating Current	80mA
Power dissipation	
Operating temperature range SCL	0°C to +70°C
Operating temperature range SCLI	
Storage temperature range	
Lead temperature, 10 seconds	+260°C
CAUTION: ECD Consistive Device. Use static control presedures in ECC	Security all and subject was not

CAUTION: ESD Sensitive Device. Use static control procedures in ESD controlled environment.

## OPERATING ELECTRICAL CHARACTERISTICS

V = +5V, V = GND,	$T_A = 25^\circ C$ ,	$V_{IN} = V_{GS} = V_{DS}$ .	IOUT = IDS(ON)	unless otherwise specified
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	ALD810030					
Parameter	Symbol	Min	Тур	Мах	Unit	Test Conditions
Gate Threshold Voltage	Vt	2.98	3.00	3.02	V	VGS = VDS; IDS(ON) = 1µA
Offset Voltage	Vos		5	20	mV	V <sub>t1</sub> - V <sub>t2</sub> or V <sub>t3</sub> - V <sub>t4</sub>
Offset Voltage Tempco	TCVOS		5		μV/C	Vt1 - Vt2 or Vt3 - Vt4
Gate Threshold Voltage Tempco	TCVt		-2.2		mV/C	$V_{GS} = V_{DS}; I_{DS(ON)} = 1 \mu A$
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.0001 26000		μΑ ΜΩ	V <sub>IN</sub> = 2.60V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.001 2700		μΑ ΜΩ	VIN = 2.70V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.01 280		μΑ ΜΩ	VIN = 2.80V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.1 29		μΑ ΜΩ	V <sub>IN</sub> = 2.90V
Output Current Drain Source On Resistance	IOUT RDS(ON)		1 3.0		μΑ ΜΩ	V <sub>IN</sub> = 3.00V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10 0.31		μΑ ΜΩ	V <sub>IN</sub> = 3.10V
Output Current Drain Source On Resistance	IOUT RDS(ON)		100 32.4		μΑ ΚΩ	VIN = 3.24V
Output Current Drain Source On Resistance	IOUT RDS(ON)		300 11.1		μΑ ΚΩ	VIN = 3.34V
Output Current Drain Source On Resistance	IOUT RDS(ON)		1000 3.52		μΑ ΚΩ	V <sub>IN</sub> = 3.52V
Output Current Drain Source On Resistance	IOUT RDS(ON)		3000 1.27		μA kΩ	V <sub>IN</sub> = 3.82V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10000 0.442		μA KΩ	VIN = 4.42V
Drain Source Breakdown Voltage	BVDSX	10.6			v	
Drain Source Leakage Current <sup>1</sup>	IDS(OFF)		10	400	pA	$V_{IN} = V_{GS} = V_{DS} = V_t - 1.0$ $V_{IN} = V_{GS} = V_{DS} = V_t - 1.0,$
Gate Leakage Current <sup>1</sup>	IGSS		5	4 200 1	nA pA nA	$T_{A} = +125^{\circ}C$ $V_{GS} = 5.0V, V_{DS} = 0V$ $V_{GS} = 5.0V, V_{DS} = 0V,$ $T_{A} = +125^{\circ}C$
Input Capacitance	CISS		15		pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 5.0V
Turn-on Delay Time	ton		10		ns	
Turn-off Delay Time	toff		10		ns	
Crosstalk			60		dB	f = 100KHz

## **ABSOLUTE MAXIMUM RATINGS**

V+ to V- voltage	15.0V
Drain-Source voltage, V <sub>DS</sub>	10.6V
Gate-Source voltage, V <sub>GS</sub>	10.6V
Operating Current	80mA
Power dissipation	500mW
Operating temperature range SAL	0°C to +70°C
Operating temperature range SALI	
Storage temperature range	
Lead temperature, 10 seconds	
CAUTION, ECD Consistive Device, Use static control precedures in	ECD controlled environment

CAUTION: ESD Sensitive Device. Use static control procedures in ESD controlled environment.

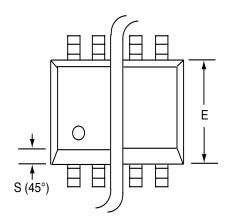
# OPERATING ELECTRICAL CHARACTERISTICS

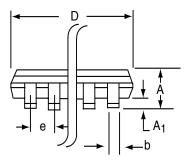
$V + = +5V, V - = GND, T_A = 3$	25°C, VIN	= VGS = VDS,	IOUT = IDS(ON)	unless otherw	ise speci	fied

	ALD910030					
Parameter	Symbol	Min	Тур	Мах	Unit	Test Conditions
Gate Threshold Voltage	Vt	2.98	3.00	3.02	V	$V_{GS} = V_{DS}; I_{DS(ON)} = 1 \mu A$
Offset Voltage	V <sub>OS</sub>		5	20	mV	V <sub>t1</sub> - V <sub>t2</sub>
Offset Voltage Tempco	TCVOS		5		μV/C	V <sub>t1</sub> - V <sub>t2</sub>
Gate Threshold Voltage Tempco	TC <sub>Vt</sub>		-2.2		mV/C	$V_{GS} = V_{DS}; I_{DS(ON)} = 1 \mu A$
Output Current Drain Source On Resistance	lout Rds(on)		0.0001 26000		μΑ ΜΩ	VIN = 2.60V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.001 2700		μΑ ΜΩ	V <sub>IN</sub> = 2.70V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.01 280		μΑ ΜΩ	V <sub>IN</sub> = 2.80V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.1 29		μΑ ΜΩ	V <sub>IN</sub> = 2.90V
Output Current Drain Source On Resistance	IOUT RDS(ON)		1 3.00		μΑ ΜΩ	V <sub>IN</sub> = 3.00V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10 0.31		μΑ ΜΩ	V <sub>IN</sub> = 3.10V
Output Current Drain Source On Resistance	IOUT RDS(ON)		100 32		μA KΩ	V <sub>IN</sub> = 3.22V
Output Current Drain Source On Resistance	IOUT RDS(ON)		300 11.0		μA KΩ	V <sub>IN</sub> = 3.30V
Output Current Drain Source On Resistance	IOUT RDS(ON)		1000 3.44		μA KΩ	V <sub>IN</sub> = 3.44V
Output Current Drain Source On Resistance	IOUT RDS(ON)		3000 1.17		μA KΩ	V <sub>IN</sub> = 3.50V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10000 0.40		μA KΩ	V <sub>IN</sub> = 4.00V
Drain Source Breakdown Voltage	BV <sub>DSX</sub>	10.6			v	
Drain Source Leakage Current <sup>1</sup>	IDS(OFF)		10	400 4	pA nA	$V_{IN} = V_{GS} = V_{DS} = V_t - 1.0$ $V_{IN} = V_{GS} = V_{DS} = V_t - 1.0$ , $T_A = +125^{\circ}C$
Gate Leakage Current <sup>1</sup>	IGSS		5	200 1	pA nA	$V_{GS} = 5.0V, V_{DS} = 0V$ $V_{GS} = 5.0V, V_{DS} = 0V,$ $T_A = +125^{\circ}C$
Input Capacitance	CISS		30		pF	VGS = 0V, VDS = 5.0V
Turn-on Delay Time	ton		10		ns	
Turn-off Delay Time	toff		10		ns	
Crosstalk			60		dB	f = 100KHz

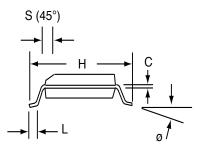
## SOIC-16 PACKAGE DRAWING

## 16 Pin Plastic SOIC Package



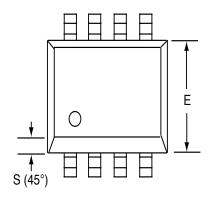


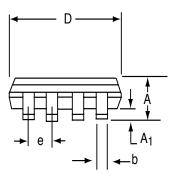
	Millim	neters	Inches		
Dim	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.25	0.004	0.010	
b	0.35	0.45	0.014	0.018	
С	0.18	0.25	0.007	0.010	
D-16	9.80	10.00	0.385	0.394	
Е	3.50	4.05	0.140	0.160	
е	1.27 BSC		0.050	BSC	
н	5.70	6.30	0.224	0.248	
L	0.60	0.937	0.024	0.037	
Ø	0°	8°	0°	8°	
s	0.25	0.50	0.010	0.020	



## SOIC-8 PACKAGE DRAWING

## 8 Pin Plastic SOIC Package





	Millim	neters	Inches		
Dim	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.25	0.004	0.010	
b	0.35	0.45	0.014	0.018	
С	0.18	0.25	0.007	0.010	
D-8	4.69	5.00	0.185	0.196	
Е	3.50	4.05	0.140	0.160	
е	1.27	BSC	0.050	BSC	
н	5.70	6.30	0.224	0.248	
L	0.60	0.937	0.024	0.037	
Ø	0°	8°	0°	8°	
S	0.25	0.50	0.010	0.020	

